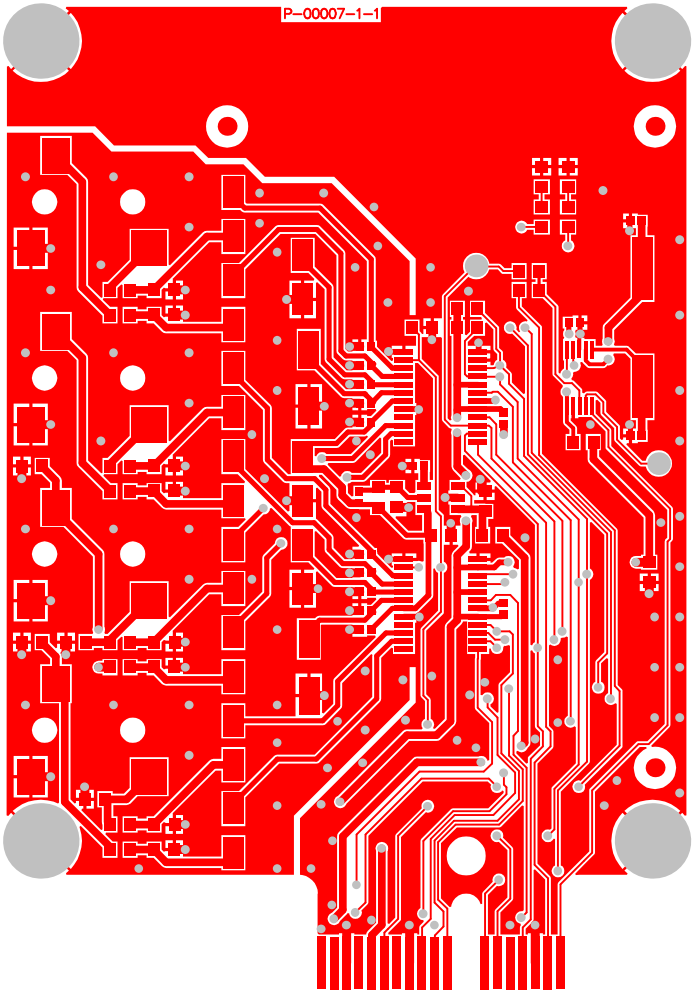


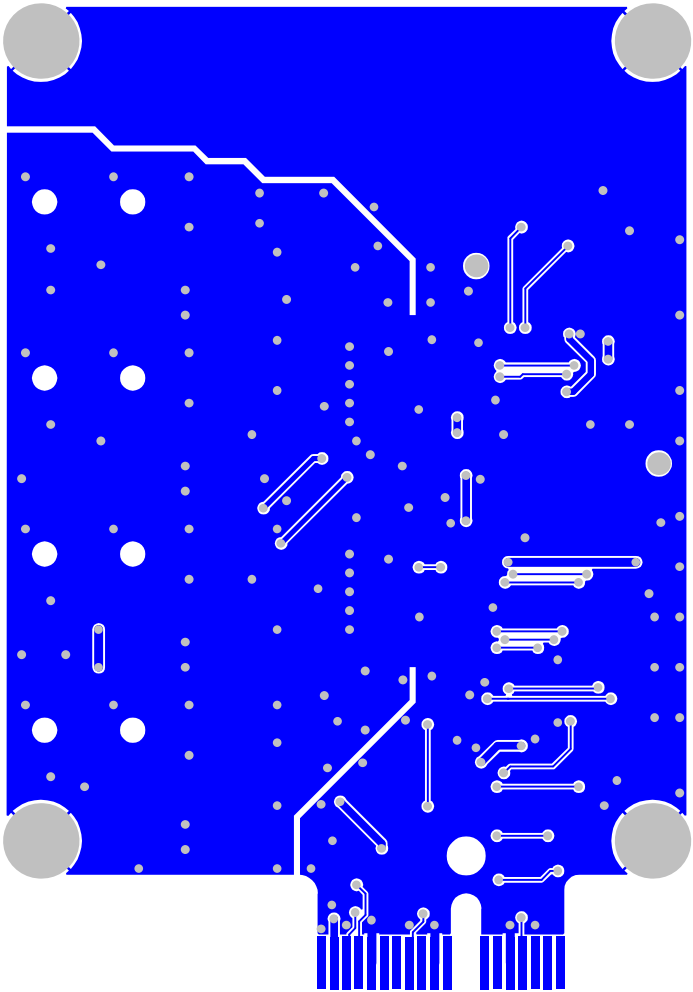
Layer 01 (Top)



XMOS LTD = P-00007-1-1-D = 07 AUGUST 2013

LAYER –  
PCB COPPER LAYER 1 (TOP)

Layer 02 (Bottom)



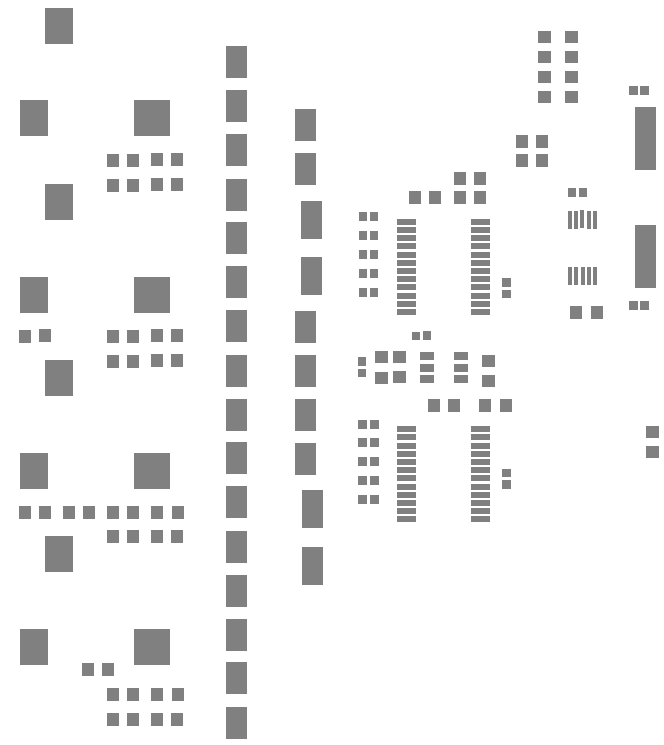
XMOS LTD = P-00007-1-1-D = 07 AUGUST 2013

LAYER -

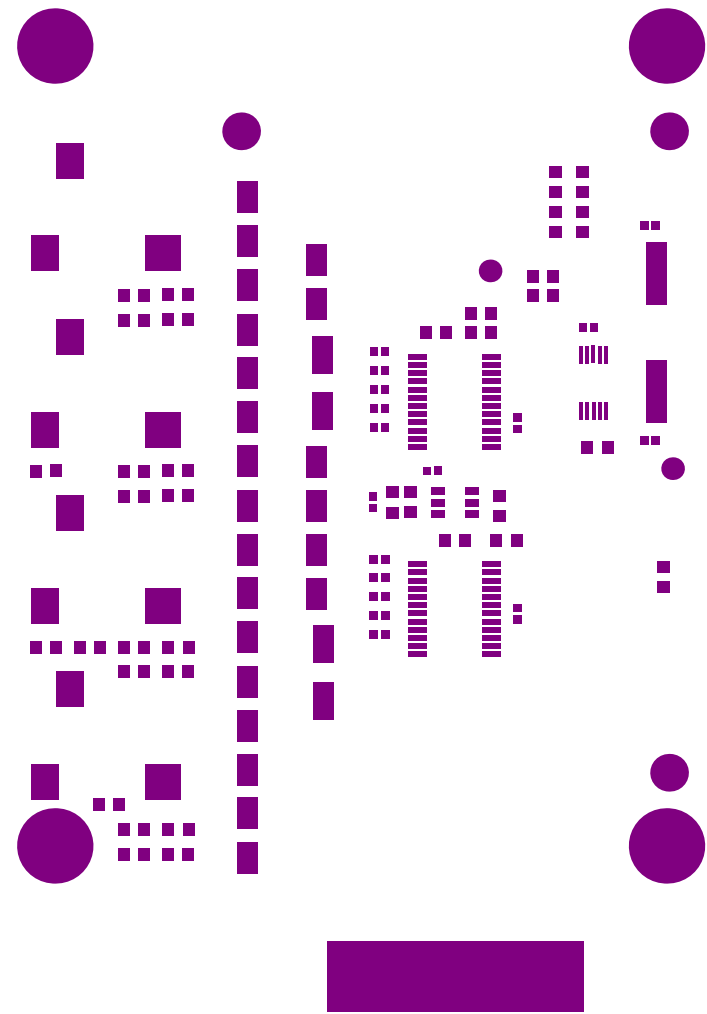
PCB COPPER LAYER 2 (BOTTOM)







PASTE MASK TOP



SOLDER MASK TOP



SOLDER MASK BOTTOM

PCB Manufacturing Notes

General Info

Board dimensions – 55mm x 80mm  
Number of layers – 2  
Smallest hole – 0.3mm  
Number of holes – Approx 210  
Minimum Track & Gap – 0.15mm  
RoHS/Lead Free – Yes  
Material – FR4 for Lead Free process

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
	0.5oz
	0.5oz

Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

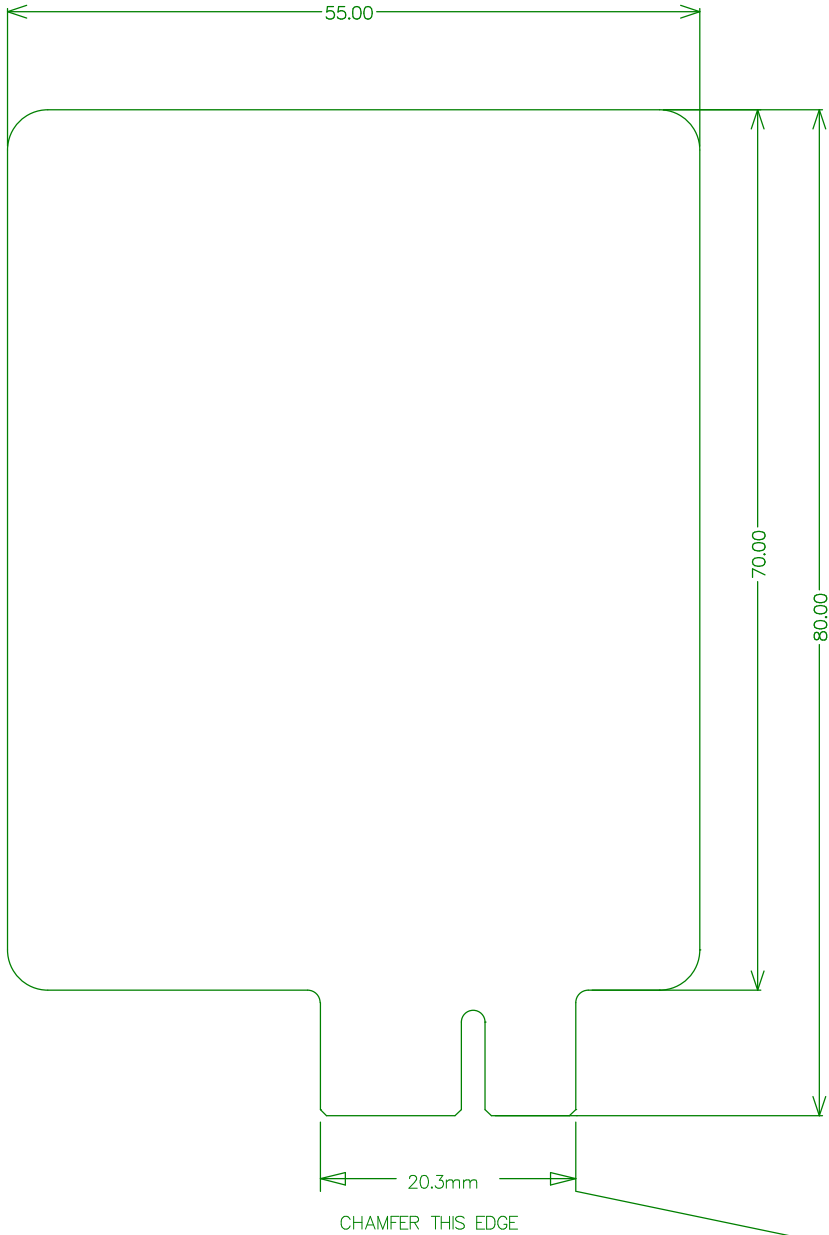
Liquid photo imageable soldermask (green). Pads have not been oversized.  
Supplier should oversize soldermask on pads to suit process.

C.) Silkscreen

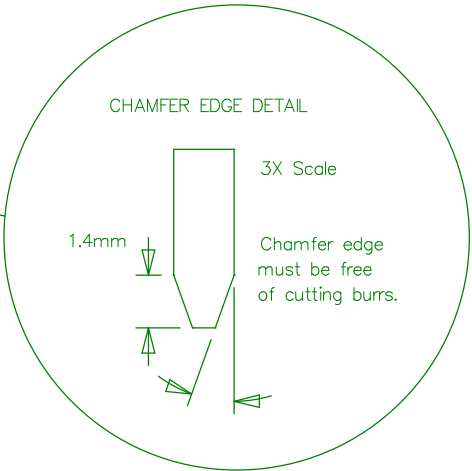
Colour white. Supplier should remove any silkscreen which overhangs pads.

Drill Data

Drill data is in Excellon format, metric (000.000), no zero suppression, absolute coordinates.  
Hole size is finished size.



FABRICATION INSTRUCTIONS



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Finish

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Plating to be immersion gold.

B.) Soldermask

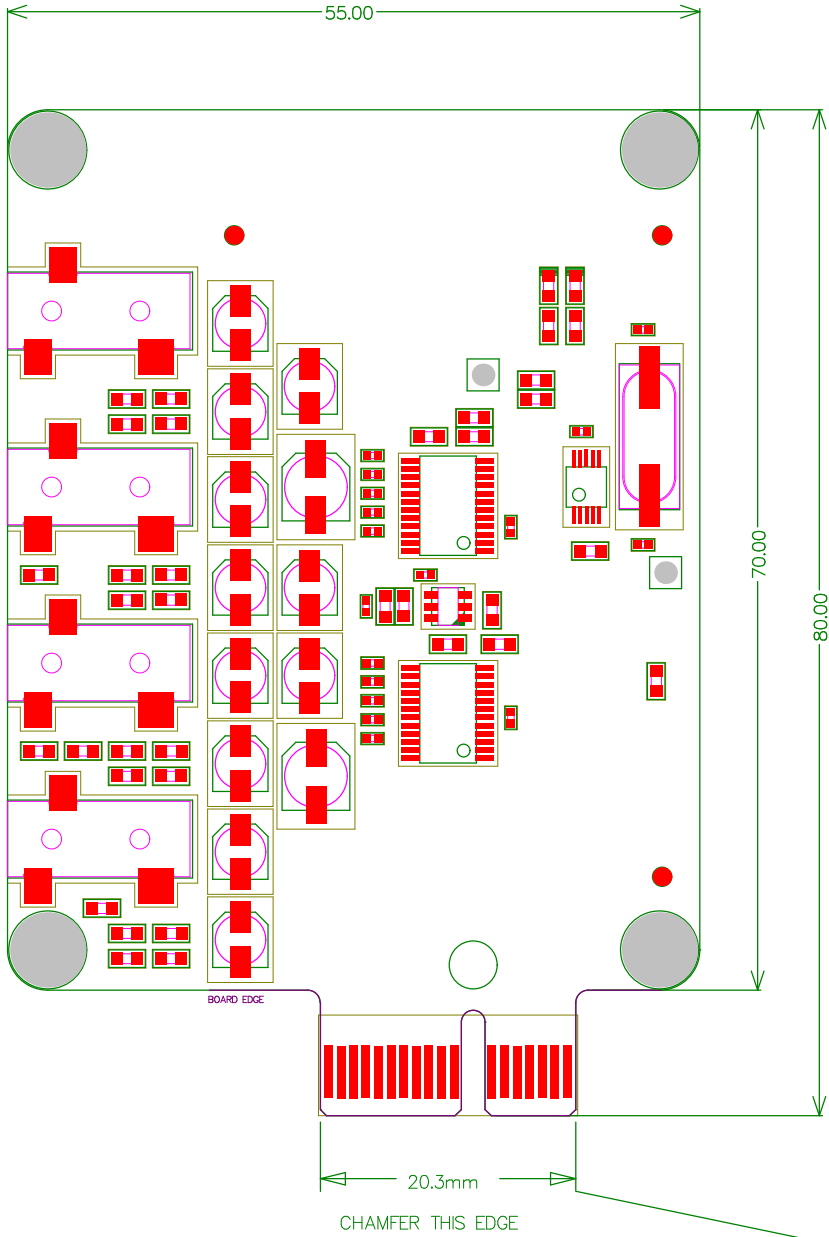
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C.) Silkscreen

Colour white. Supplier should remove any silkscreen which overhangs pads.

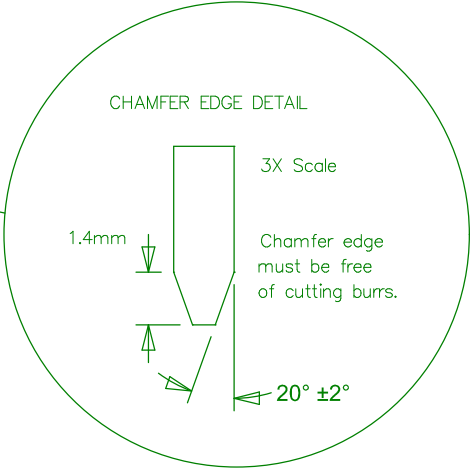
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FABRICATION INSTRUCTIONS

ASSEMBLY DRAWING TOP  
ASSEMBLY DRAWING BOTTOM



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B.) Soldermask

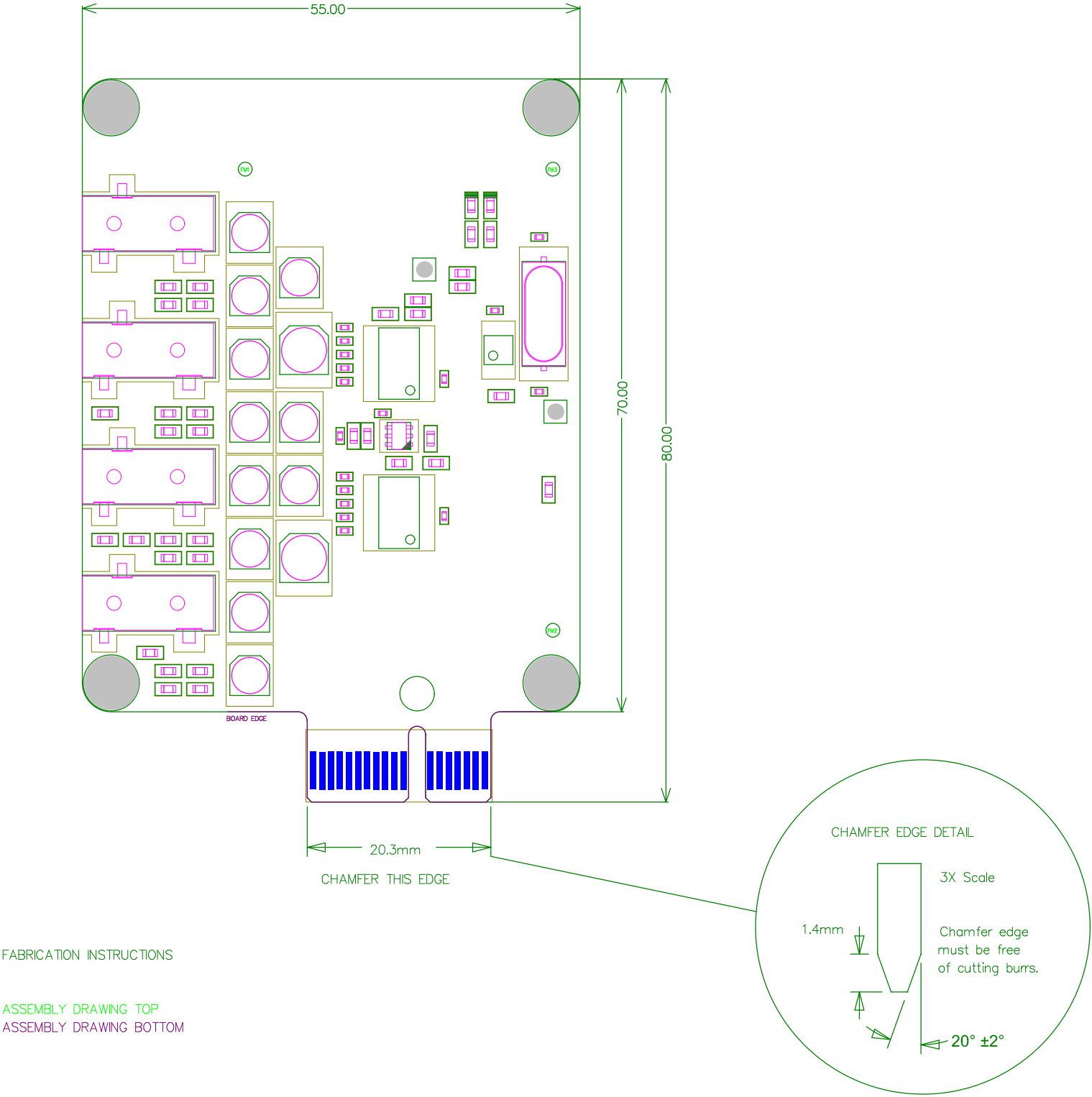
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B.) Soldermask

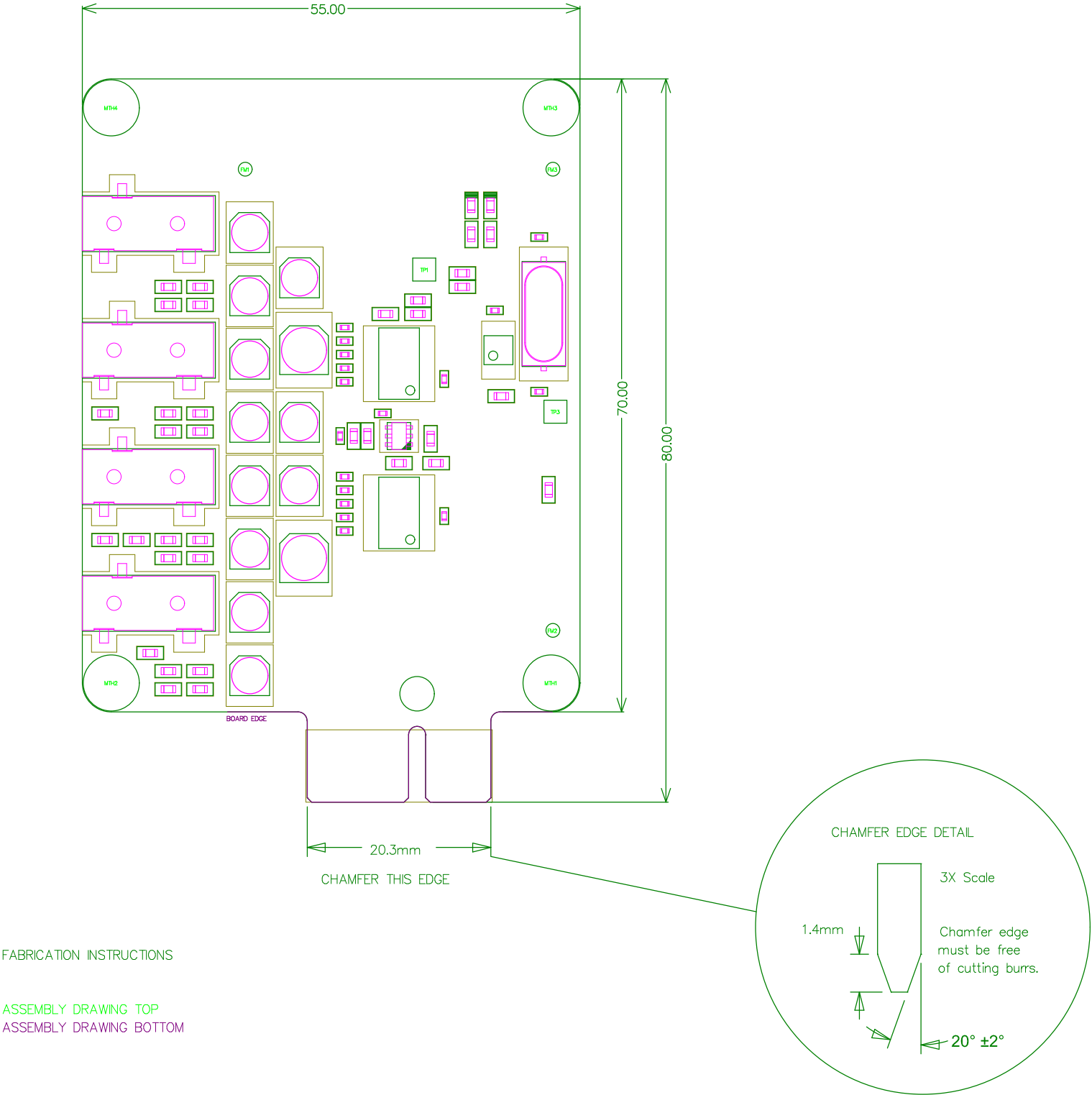
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FABRICATION INSTRUCTIONS

ASSEMBLY DRAWING TOP  
ASSEMBLY DRAWING BOTTOM

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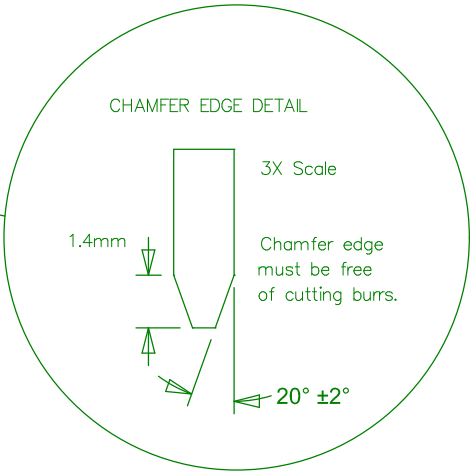
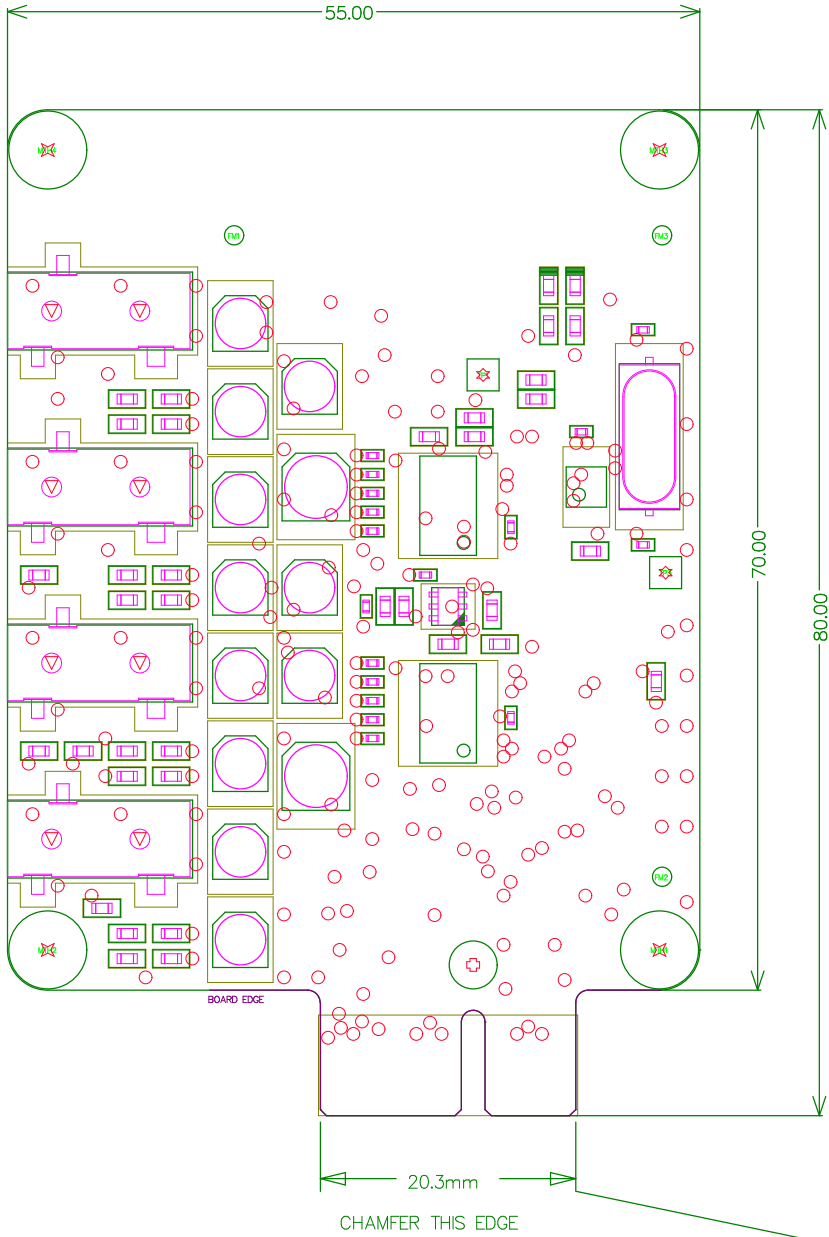
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FABRICATION INSTRUCTIONS

DRILL DRAWING

ASSEMBLY DRAWING TOP  
ASSEMBLY DRAWING BOTTOM

Symbol	Hit Count	Tool Size	Plated	Hole Type
○	198	0.3mm (11.811mil)	PTH	Round
☆	2	1mm (39.37mil)	PTH	Round
▽	8	1.7mm (66.929mil)	NPTH	Round
⊕	1	2.8mm (110.236mil)	NPTH	Round
⊗	4	3.2mm (125.984mil)	PTH	Round
	213 Total			

Drill Drawing.

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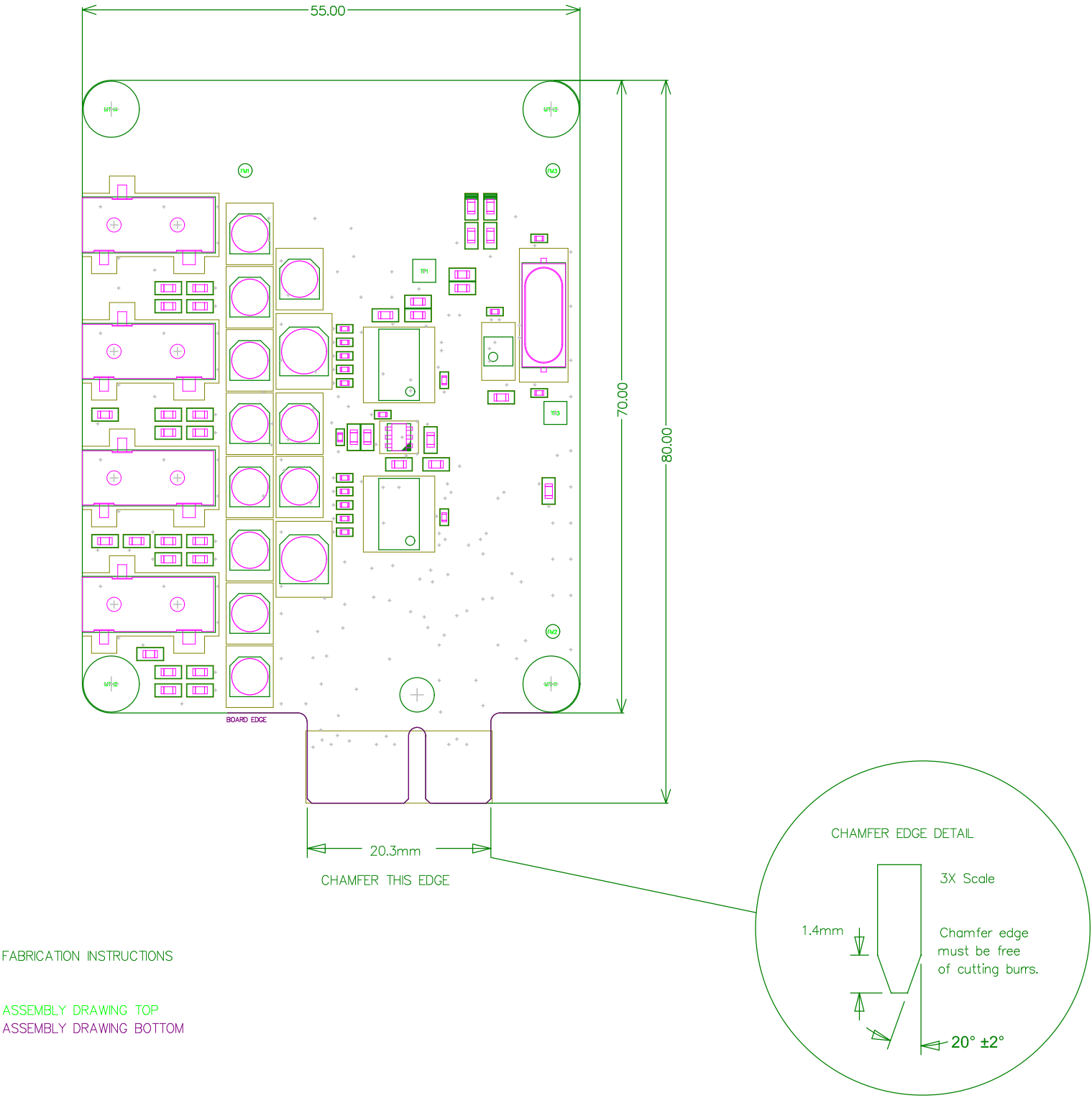
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FABRICATION INSTRUCTIONS

ASSEMBLY DRAWING TOP  
ASSEMBLY DRAWING BOTTOM

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